

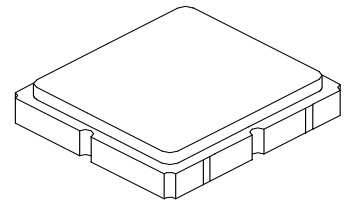
- Low-loss RF SAW Filter
- Surface Mount 3.0 x 3.0 x 1.3 mm Package
- Complies with Directive 2002/95/EC (RoHS)
- Moisture Sensitivity Level: 1

Absolute Maximum Ratings

Rating	Value	Units
Input Power Level	10	dBm
DC Voltage on any Non-ground Terminal	3	V
Operating Temperature Range	-30 to +85	°C
Storage Temperature Range in Tape and Reel	-40 to +95	°C
Solder Reflow Temperature, 10 seconds, 5 cycles maximum	260	°C

SF2240E

**2595 MHz
SAW Filter**



SM3030-6

Electrical Characteristics

Characteristic	Sym	Notes	Min	Typ	Max	Units
Center Frequency	F _C			2595		MHz
Maximum Insertion Loss, 2575 to 2615 MHz	IL			3.2	4.0	dB
Amplitude Ripple, 2575 to 2615 MHz				1.6	2.2	dB _{p-p}
VSWR, 2575 to 2615 MHz				1.4:1	2.3:1	
Attenuation Referenced to 0 dB:						
DC to 1100 MHz			37	42		dB
1100 to 2100 MHz			31	42		
2100 to 2465 MHz			40	43		
2465 to 2530 MHz			10	20		
2665 to 2675 MHz			10	30		
2675 to 2695 MHz			35	48		
2695 to 4000 MHz			30	36		
Frequency Temperatue Coefficient				-36		ppm/K
Source Impedance	Z _S			50		Ω
Load Impedance	Z _L			50		
Case Style	SM3030-6 3.0 x 3.0 mm Nominal Footprint					
Lid Symbolization (Y=year, WW=week, S=shift) dot=pin 1 indicator	974, <u>YWWS</u>					
Standard Reel Quantity	Reel Size 7 Inch	500 Pieces/Reel				
	Reel Size 13 Inch	3000 Pieces/Reel				

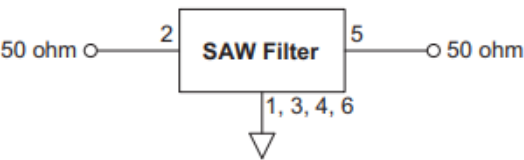


CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.

NOTES:

1. The design, manufacturing process, and specifications of this device are subject to change.
2. US or International patents may apply.
3. RoHS compliant from the first date of manufacture.

Filter Test Circuit

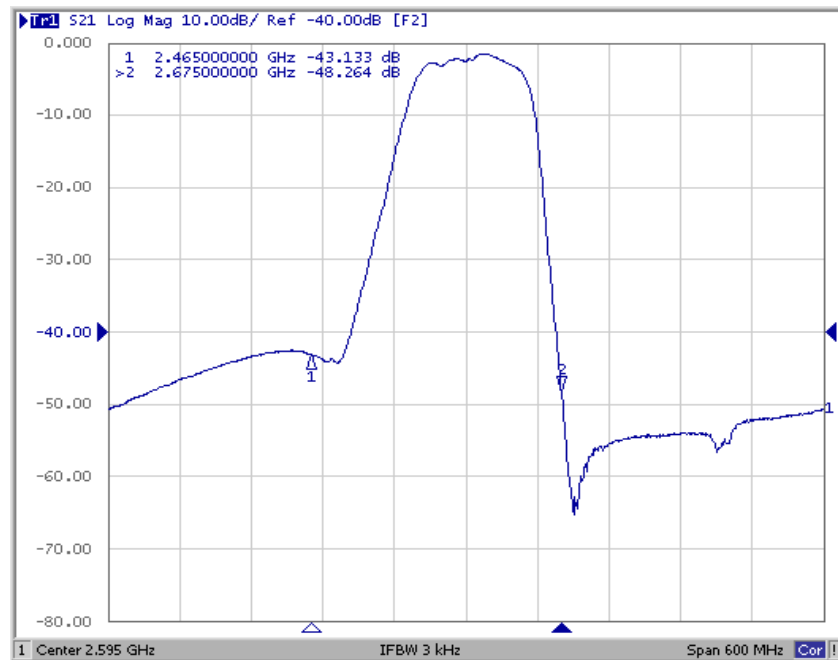


Connection	Terminals
Input	2
Output	5
Ground	All Others

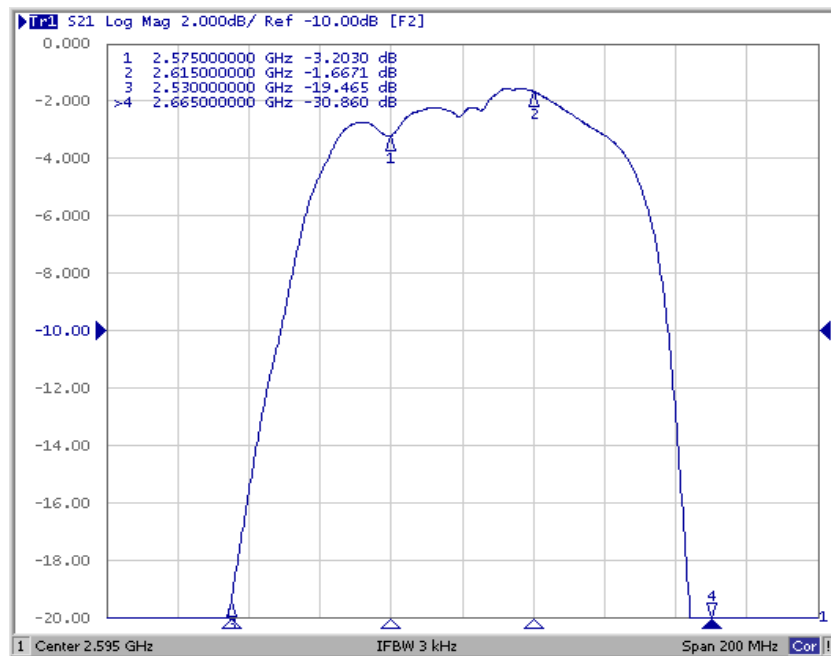
Filter Broadband Response, 10 to 4000 MHz



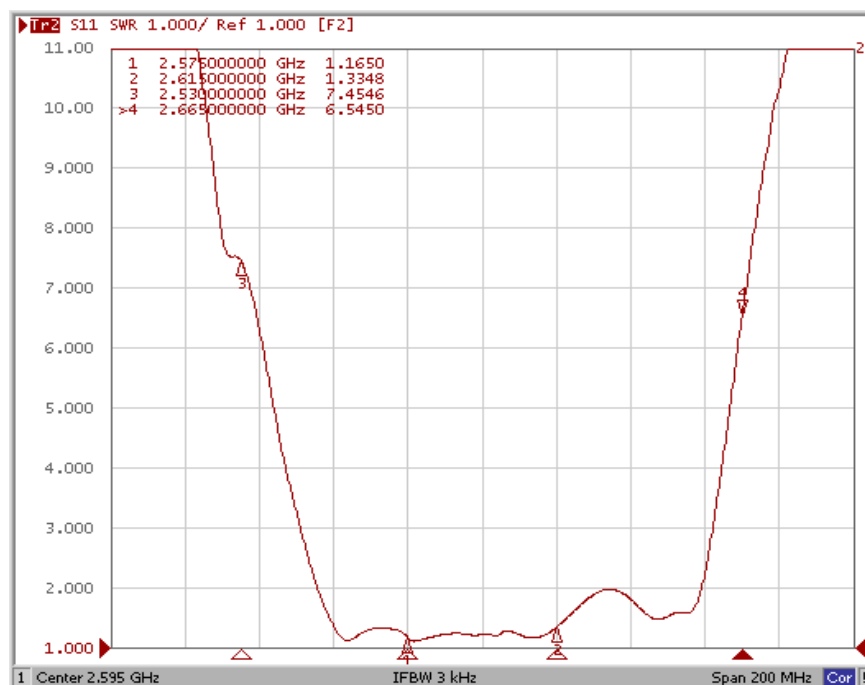
Filter Plot, 2295 to 2895 MHz



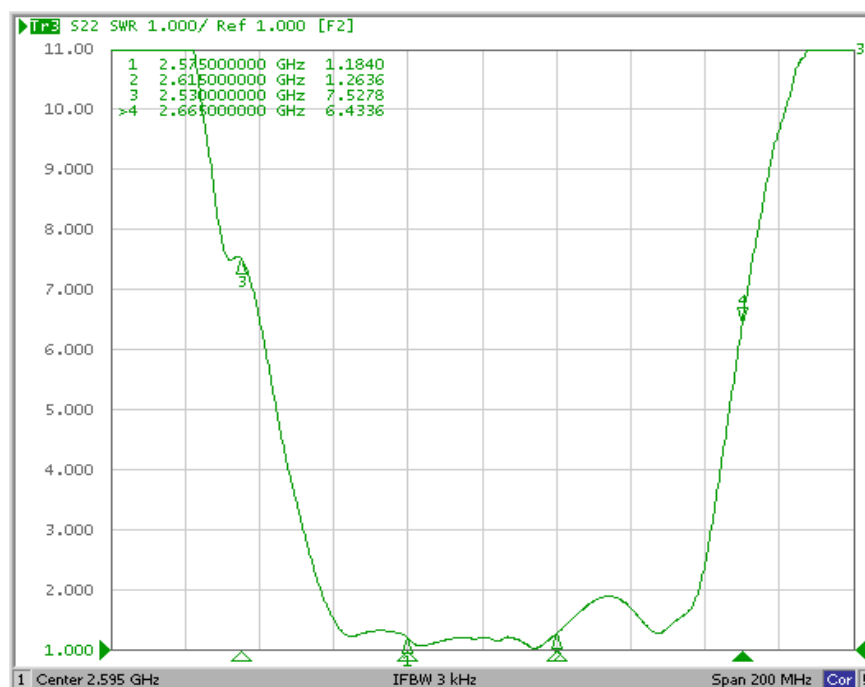
Filter Passband Plot, 2495 to 2695 MHz



Filter Input VSWR Plot, 2495 to 2695 MHz

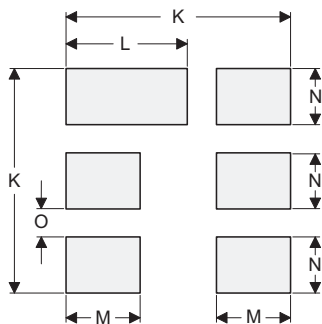
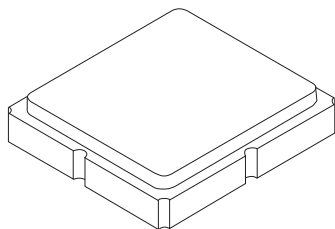


Filter Output VSWR Plot, 2495 to 2695 MHz



SM3030-6 Case

6-Terminal Ceramic Surface-Mount Case 3.0 X 3.0 mm Nominal Footprint



PCB Footprint Top View

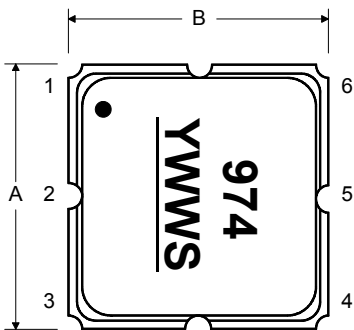
Case and PCB Footprint Dimensions

Dimension	mm			Inches		
	Min	Nom	Max	Min	Nom	Max
A	2.87	3.00	3.13	0.113	0.118	0.123
B	2.87	3.00	3.13	0.113	0.118	0.123
C	1.12	1.25	1.38	0.044	0.049	0.054
D	0.77	0.90	1.03	0.030	0.035	0.040
E	2.67	2.80	2.93	0.105	0.110	0.115
F	1.47	1.60	1.73	0.058	0.063	0.068
G	0.72	0.85	0.98	0.028	0.033	0.038
H	1.37	1.50	1.63	0.054	0.059	0.064
I	0.47	0.60	0.73	0.019	0.024	0.029
J	1.17	1.30	1.43	0.046	0.051	0.056
K		3.20			0.126	
L		1.70			0.067	
M		1.05			0.041	
N		0.81			0.032	
O		0.38			0.015	

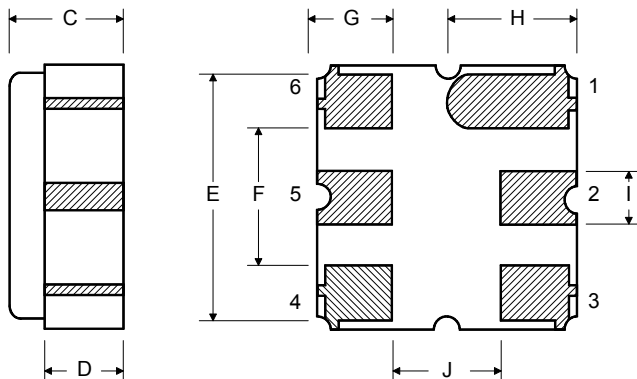
Case Materials

Materials	
Solder Pad Plating	0.3 to 1.0 μ m Gold over 1.27 to 8.89 μ m Nickel
Lid Plating	2.0 to 3.0 μ m Nickel
Body	Al ₂ O ₃ Ceramic

TOP VIEW

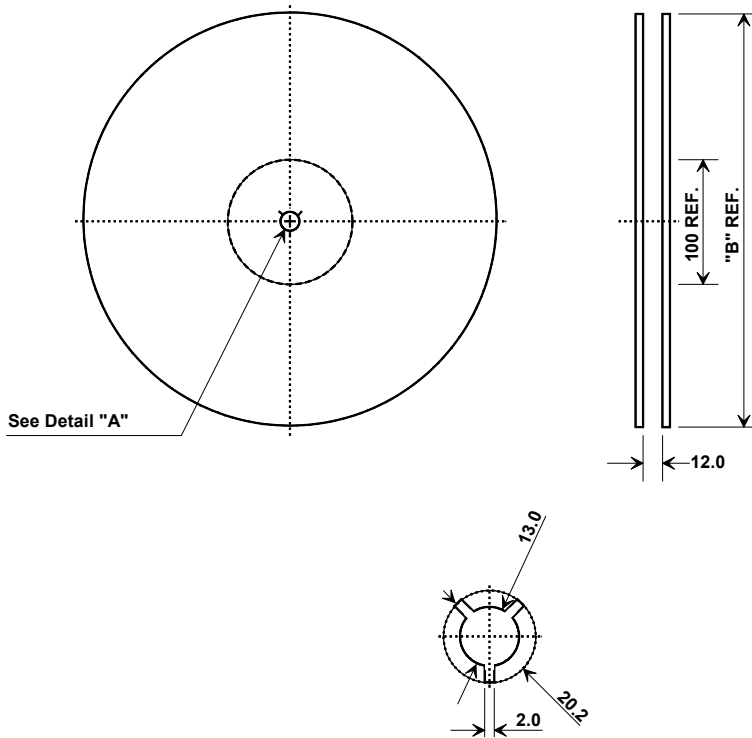


BOTTOM VIEW



Tape and Reel Specifications

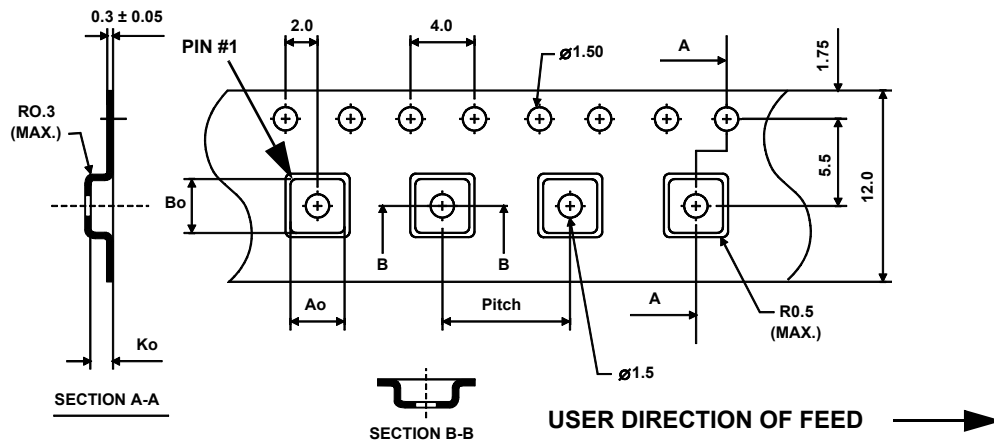
Tape and Reel Standard per ANSI/EIA-481



"B"		Quantity Per Reel
Inches	millimeters	
7	178	500
13	330	3000

COMPONENT ORIENTATION and DIMENSIONS

Carrier Tape Dimensions	
Ao	3.35 mm
Bo	3.35 mm
Ko	1.40 mm
Pitch	8.0 mm
W	12.0 mm



Recommended Reflow Profile

1. Preheating shall be fixed at 150~180°C for 60~90 seconds.
2. Ascending time to preheating temperature 150°C shall be 30 seconds min.
3. Heating shall be fixed at 220°C for 50~80 seconds and at 260°C +0/-5°C peak (10 seconds).
4. Time: 5 times maximum.

